Quik-Pak™
A Division of Promex Industries Incorporated

BGA/Flip Chip/ COB
Assembly Build Sheet

Original request

Changed request   Rev # _____

QP Internal S.O. #: _____

QP Sales Contact: _____

QP Quote #: _____

CUSTOMER CONTACT INFORMATION

Company: _____   Contact Name:_____   Date_____

Phone: _____   Email:_____

P.O. #: _____

Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)?   Yes   No

DELIVERY REQUEST

LEAD TIMES WILL VARY BASED ON SCOPE OF WORK AND QUANTITY. STANDARD LEAD TIME FOR BENCHMARK ORDER (PKG: BGA, PKG QTY: <50, F/C OR WIRE COUNT: <100, SINGLE DIE ATTACH) IS 5 DAYS. EXPEDITE (3-4 DAYS). PREMIUM (<2 DAYS). SEE QUOTE FOR DELIVERY CYCLE SPECIFIC TO YOUR BUILD.

Standard   Expedite   Premium

DIE INFORMATION:

ALL WAFER PROCESSING REQUIRES A BACKGRIND/DICING BUILD SHEET TO BE COMPLETED AND ATTACHED SEPERATELY.

Die Format: Waffle Pack   Gel-Pak   Diced Wafer on Tape   Wafer (requires processing)   Other: _____

Die Size: _____ X _____ μm or mils

Pad Pitch: _____ X _____ μm or mils

Bond Pad Dims: _____ X _____ μm or mils

Bond Pad Opening: _____ X _____ μm or mils

Thickness: _____ μm or mils

(a) Wafer ID/Die ID:	(b) Lot #	(c) Qty of Devices to be Assembled from ID
1a. _____	1b. _____	1c. _____
2a. _____	2b. _____	2c. _____
3a. _____	3b. _____	3c. _____
4a. _____	4b. _____	4c. _____

Metalization: Aluminum   Gold   Other (Specify): _____   Probed?   Passivated?   Cu Pillar w/ SAC Top?

Bump Metallurgy: Leaded   Lead-Free   Gold   Other: _____   Bump Diameter: _____   Bump Height: _____

DEVICE INFORMATION

Assembly Type: Flip Chip   Wire bond

Device Name: _____   Bump/Lead Pitch: _____   Die Per Package: _____   Bumps/Wire Count Per Package: _____

Qty of Devices to be Assembled: _____   Package Dimension (mm): ____ X ____   Package Description: _____

Packages provided by: Customer   Quik-Pak   Packages Require Opening (OcPP)

Package Type*:   BGA   COB   Other: _____   BGA Package Outline Drawing Number: _____

*FOR BGA PACKAGES, A PACKAGE OUTLINE DRAWING MUST BE INCLUDED.

SPECIAL INSTRUCTIONS (ATTACH ADDITIONAL DOCUMENTS IF NEEDED)

_____

_____

_____

_____

CUSTOMER FURNISHED MATERIALS:

PLEASE LIST ANY ADDITIONAL CFMs THAT WILL BE SHIPPED TO QUIK-PAK. IF MORE SPACE IS NEEDED, PLEASE ATTACH ADDITIONAL DOCUMENTS.

1. _____   2. _____   3. _____

4. _____   5. _____   6. _____

7. _____   8. _____   9. _____

WIRE BOND ASSEMBLY FLOW

ALL WIRE BONDING REQUIRES A BONDING DIAGRAM BE ATTACHED WITH CLEARLY LABELED PIN 1, DIE ORIENTATION, AND WIRES BONDS.

Please Indicate The File Format:　　CAD Drawing　　Other (JPEG, PowerPoint, PDF, etc.)

Select Die From:　　Center of Wafer(s)　　Wafer Map(s)

Die Attach Material (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT MATERIALS):

_____ Conductive Epoxy　　　　　_____ Thermally Conductive/Electrically Non-Conductive

_____ Non-Conductive Epoxy　　　_____ Material High Thermally/Electrically Conductive Material

Gold Wire Diameter (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT WIRE DIAMETER):
　　*STANDARD MATERIAL. OTHER OPTIONS MAY INCREASE COST/LEADTIME.

____ 0.7 mil　　____ 0.8 mil　　____ 1.0 mil*　　____ 1.2 mil

____ 1.3 mil　　____ 1.5 mil　　____ 2.0 mil　　____ Other (Al available - call for wire size)

Heavy Wire:　____ 5 mil　　____ 10 mil　　____ 15mil　　____ 20mil

Gold Ribbon:　____ 1 X 2 mil　　____ 1 X 3 mil　　____ 1 X 4 mil

Seal (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT SEALING METHODS):

____ None　　　　　　　　　　　　　____ Encapsulation Around Wires Only　　　____ Overmolded

____ Standard Full Encapsulation (Glop Top)　____ Frame & Lid (For Non-Solder Applications)

____ Clear encapsulant (UV Cure)　　　____ Other　(Specify) _____

FLIP CHIP ASSEMBLY FLOW

ALL FLIP CHIIP ORDERS REQUIRE DRAWING WHICH INCLUDES BUMPED DIE ORIENTATION TO PACKAGE.

Underfill Required?　　Temp Constraints　　If yes, max _____°C

Flip Chip Method:

Thermocompression (T≥280°C; Recommended for ceramic or high temp organic substrate; Au bumps on I/O's required)

Thermosonic (T=150-180°C; Recommended for organic substrates; Au bumps on I/O's required)

Eutectic (Recommended for ceramic or organic substrates; Solder balls required)

MARKING

(MAX CHARACTER LENGTH AND NUMBER OF ROWS WILL VARY BASED ON PACKAGE SIZE. CONTACT QP FOR DESIGN APPROVAL AND COSTS.):
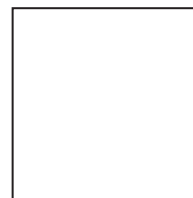
Mark pin 1 on device?

Custom Design

No Custom Marking

Hand Mark (Max. 1-3 characters): _____

Pad Print (White on Black) - E-mail artwork in native .EPS or .AI file format

Laser Mark (Black on Black) - E-mail artwork in native .EPS or .AI file format

Serialization (MAY INCREASE MARKING COSTS/LEADTIME). Please describe:

_____

Mark pin 1 corner and indicate how marking should appear on package relative to pin 1.

SHIPPING (Contact QP with any special requests)

Reject Parts Disposition (UNLESS OTHERWISE NOTED ALL EXTRA MATERIALS WILL BE RETURNED):　　Return to Customer　　Bag and Tag　　Destroy

Shipping Method (Please Select)　　　　　　　　Account #: _____

Pickup　　　　FedEx　　　　DHL　　　　UPS　　　　Courier　　　　Special Instructions

Ship To Address (Finished Product):

Attn: _____

Address: _____

_____

Include Certificate of Conformance

Ship Materials In:

Trays

Tubes

Other: _____

Containers Provided By:

Quik-Pak

Customer

Ship To Address (Excess Die and Materials):

Attn: _____

Address: _____

_____

For Quik-Pak Internal Use Only:

Orders meeting one of the following requirements require signatures by representatives in the following departments:

[] Over $20k   [] ISO-13485 Processing   [] Change in instructions after order has been released to production

Sales:_____ Date:_____

Engineering:_____ Date:_____

Manufacturing:_____ Date:_____

QA:_____ Date:_____

Per Quik-Pak quality program, risk assessment is required on orders over $100k and/or Medical orders built under ISO-13485 std.